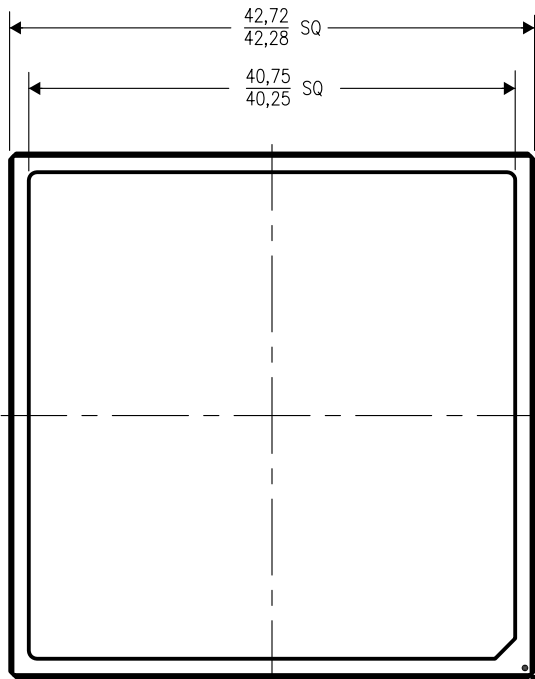


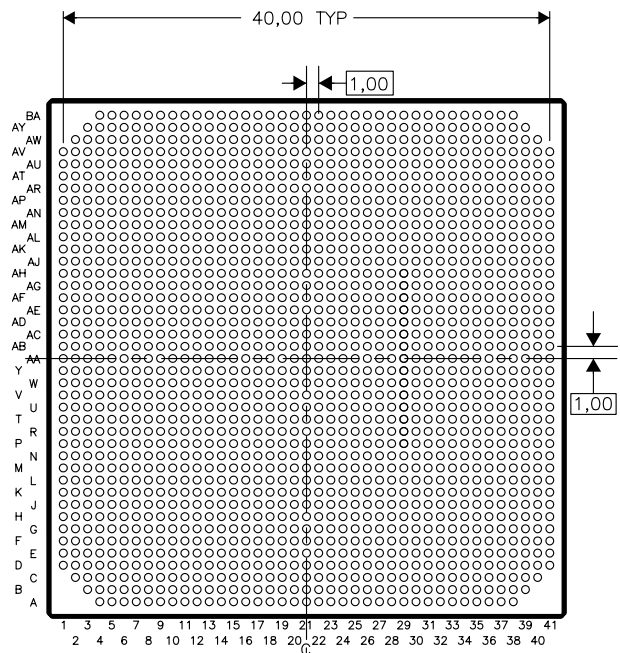
MECHANICAL DATA

GTJ (S-CBGA-N1657)

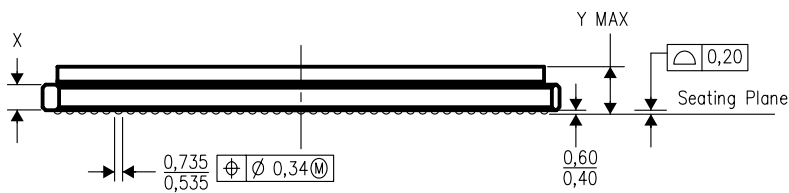
CERAMIC BALL GRID ARRAY



PIN A1 CORNER



BOTTOM VIEW



THICKNESS		DIM	
		A	B
X	MAX	2,20	1,76
X	MIN	1,80	1,44
Y		4,50	4,10

4205014-3/D 01/04

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Thermally enhanced ceramic package with a heat slug (HSL).
 - Flip chip application only.

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